PicoTrack

semi MEMBER
www.picotrack.com

309 Laurelwood Rd #21
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Main: (408)988-7000
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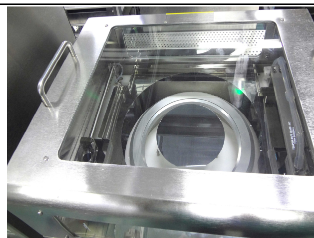
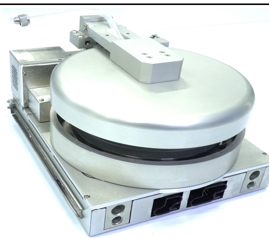
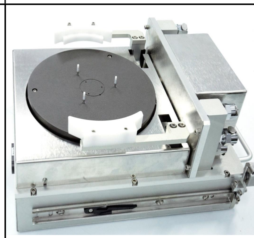
PCT-200CRS TRACK SYSTEM

STANDARD PRODUCTION or R&D WITH SINGLE TRACK (1 COATER, 1 DEVLOPER) TOOL SET

Please contact Sales sales@picotrack.com for more information

Coater Module	Developer Module	VPO Module	HPO Module	CP Module
				

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Track System Specification	Description
System designed	US Standard System
System Configuration (*Configuration available upon request)	DEV: VPO | HPO DEV: HPO | HPO DEV: CP | CP DEV: CP-CENT | CP-CENT SHUTTLE ARM COAT: SEND | SEND COAT: REC | REC
System dimension	Length: 53" ; Width: 50" ; Height: 90"
Wafer size (workable dual size)	Up to 8" (200mm) or 6" & 8" auto conversion
Wafer shape	Round/Square/Rectangular/Triangle/Special
Wafer material	Silicon/Sapphire/GaAs/ Ceramic…
Wafer sensor	Optical sensor mapping
System controller	PC & PLC Controller with Windows OS based
Chemical canister cabinet	Solvent (EBR, HMDS, Cleaning…), developer liquid
Pumps cabinet	Photoresist pumps (IDI, Cybor..), dispenser unit, & photoresist bottles
Indexer wafer cassettes capacity	4 or 8 (available upon request)
Shuttle Robot Arm	2 Robot arm and dual end effectors
System Fan Filter Unit (FFU)	optional
System SECs/GEM	optional
Coater	**1 module**
Catch Cup Set	Up/down motion
Spindle Unit	Fixed position
Maximum spin speed	7000 rpm
Spin motor type	Servo
Spin speed accuracy	± 3 rpm
Acceleration range	0-50000 rpm/sec
Dispense arm accuracy	± 0.1 mm
Wafer centering	± 0.1 mm
Dispense arm motion control	Stepper motor drive and rotation
Dispense arm # 1 & nozzles	3x or more (3/16" or 1/4" OD) (Standard)
Dispense arm # 2 & nozzles	3x or more (3/16" or 1/4" OD) (Optional)
Dispense method	Static, radial and traverse
Pre-dispense function	Yes
Top/Bottom EBR	Yes
Catch-cup rinse(CCR)	Optional
Cleaning tip nozzle	Optional
Humidity & Temperature control	Optional
Photoresist temperature control	Optional (≤ 1°C; 10-50°C range)
Coating type	Regular, SOG, PG, and Spray (available upon request)
Developer	**1 module**
Catch Cup Set	Up/down motion
Spindle Unit	Fixed position

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Maximum spin speed	7000 rpm
Spin motor type	Servo
Spin speed accuracy	± 3 rpm
Acceleration range	0-50000 rpm/sec
Spin direction	Clockwise (+) & counter clockwise (-)
Dispense arm motion control	Stepper motor drive and rotation
Dispense arm accuracy	± 0.1 mm
Wafer centering tolerance	± 0.1 mm
Dispense arm # 1 nozzles	1 Spray+ 1 Stream or 2 spray+ 2 stream (Standard)
Dispense arm # 2 nozzles	1 Spray+ 1 Stream or 2 spray+ 2 stream (Upon request)
Negative developer nozzles	Cone or fan spray with N2 air assist (Upon request)
Developer dispense type	Stream, Puddle, Fan spray, Cone spray….
Dispense method	Static, radial and sweep
DI water top and back side rinse	Yes
N2 Air Ring back side	Yes
N2 Blow-off top nozzle	Optional
Developer liquid Temp. controller	Optional (≤ 1°C; 10-50°C range)
Vapor Prime Ovent (VPO)	**1 module (Stack up)**
VPO block type	Aluminum anodized with vacuum slots
VPO Temperature controller	Watlow P.I.D with over heating protection
Temperature thermal probe	RTD or TC
Temperature range	Up to 200°C, Δt: 50°C ≤ 200s
Temperature uniformity	± 1°C (25-15°0C), ± 2°C (151-200°C)
HMDS prime method	Fume shower nozzles on top by pressurized N2 with bubbler
Wafer contact angle	≥ 65° on prime silicon wafer
Contact angle uniformmity	≤ 1.5° on prime base silicon wafer
Wafer Carrier	3 pins controlled by stepper motor
Bake method	Contact, vacuum & purge bake
Hot Plate Oven (HPO)	**3 modules (Stack up)**
HPO block type	Aluminum anodized with vacuum slots or proximity
HPO Temperature controller	Watlow P.I.D with over heating protection
Temperature thermal probe	RTD or TC
Temperature range	25-250°C, Δt: 50°C ≤ 200s (>250°C option)
Temperature uniformity	± 1°C (25-150°C), ± 2°C (151-250°C)
Wafer Carrier	3 pins controlled by stepper motor
Bake method	Contact/ Proximity bake/ or fixed proximity
Chill Plate & Centering (CP-CENT)	**4 modules (Stack up)**
Chill Plate block type	Aluminum anodized with vacuum slots or proximity
Chill Plate Temperature control	House cooling water with flowmeter (18°C to 30°C)
Chill method	Contact or proximity
Cooling Water Temp. controller	Optional
Wafer Carrier	3 pins controlled by stepper motor or cylinder
Wafer Centering	Integrated